A B S T R A C T

A surface acoustic wave device is obtained at low cost in a small size while good airtightness of a vacant portion is maintained. For this purpose, the surface of a surface acoustic wave element (40), on which an inter digital transducer is formed, is connected to a flat-plate substrate (100) by means of a bump with a vacant portion (50) formed between them. In this structure, a stepped portion (111) having a step is formed on the surface of the substrate at the edge. When the surface of the stepped portion and the outer surface of the surface acoustic wave element are covered together with a hardening resin (60), the hardening resin (60) coincides with the stepped portion to attain the airtightness of the vacant portion.



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